Bringing science to comfortable living through advanced Kiru, Kezuru, Migaku technologies.

ISO Certification

- Thickness measurement (Laser/Capacitive)
- Die strength measurement
- Automatic Optical Inspection
- Inspection microscope
- Automatic tracking system via internet platform for customers
- High process traceability

Contact

DISCO HI-TEC EUROPE GmbH
Liebigstraße 8
85551 Kirchheim b. München
Germany
Phone: +49 (0)89 90903-0
Fax: +49 (0)89 90903-199
E-mail: dgs@discoeurope.com
Web: www.dicing-grinding.com

High Quality

- Dicing
- Kiru
- Grinding
- Kezuru
- Polishing
- Migaku
- Special Solutions
All DGS applications are offered for various materials up to 300 mm in combination with:
- Wafer lamination
- Wafer mounting
- UV irradiation of tapes
- Inspection (chipping, die strength testing, etc.)
- Vacuum sealed packaging under N2

**Dicing | Kiru**
- Single cut
- Step cup
- Bevel cut
- Grooving
- Chopper cut
- Circle cut
- Edge trimming

**Polishing | Migaku**
- Dry polishing
- Stress relief process for higher die strength and reduction in die warpage

**The New Cleanroom** Open since Summer 2013
- Floor size: 400 m²
- Number of Machines: 30+
- Now added: CAMTEK Automatic Inspection Tool Condor 200 Series

**Grinding | Kezuru**
- Standard grinding
- Ultra-Thin grinding
- Bonded Wafer grinding
- Partial Wafer grinding
- Individual Die grinding
- Edge trimming
- Poligrind / Ultrapoligrind

**Special Solutions for high-end applications:**
- Dicing Before Grinding (DBG)
- Plasma etching for high die strength
- TAIKO for power devices <100 µm
- Surface planarization
- Stealth Laser for various materials
- Ultrasonic dicing
- IR/White light

**Floor size:**

**Number of Machines:**

**Now added:** CAMTEK Automatic Inspection Tool Condor 200 Series